

Description

This is CT56N02ZT Dual N-Channel Enhancement Mode MOSFET uses advanced power trench technology that has been especially tailored to minimize the on-state resistance This device is suitable for un-directional or bidirectional load switch, facilitated by its common-drain configuration.

Features

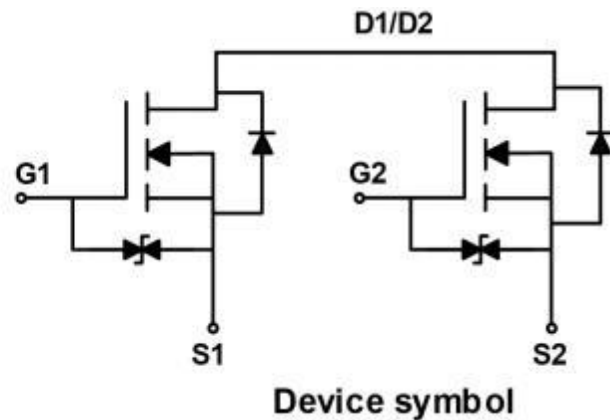
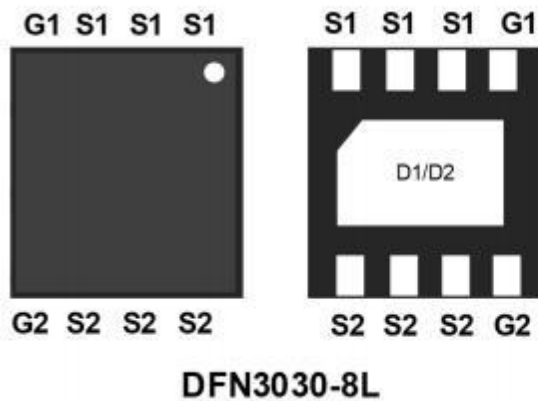
- Super high dense cell for low RDS(ON)
- RoHS Compliant and Halogen-Free
- ESD protected: Class 2

Applications

- Battery protection
- Load switch

V_{DS}	$R_{DS(on)}$ ($V_{GS}=4.5V$)	I_D
20V	4.2m Ω	56A

Schematic & PIN Configuration



Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	±12	V
Continuous Drain Current	T _A =25°C	I_D	56	A
	T _A =70°C		20	A
Pulsed Drain Current ¹		I_{DM}	210	A
Single Pulse Avalanche Energy ⁵		E_{AS}	64.8	mJ
Avalanche Current		I_{AS}	36	A
Total Power Dissipation	T _A =25°C	P_D	3.6	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C
Maximum Junction-to-Ambient ²		R_{θJA}	35	°C/W

Electrical Characteristics (Tamb=25° C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	μA
Gate-body Leakage Current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±8V	-	-	±10	μA
Gate-Threshold Voltage ³	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.45	-	1.0	V
Drain-Source on-Resistance ³	R _{DS(on)}	V _{GS} = 4.5V, I _D = 3A	3.5	4.2	5.8	mΩ
		V _{GS} = 3.9V, I _D = 3A	3.7	4.3	6.5	
		V _{GS} = 3.1V, I _D = 3A	3.8	4.7	6.8	
		V _{GS} = 2.5V, I _D = 3A	4	5	7	
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 10V, V _{GS} =0V, f =1MHz	-	3165	-	pF
Output Capacitance	C _{oss}		-	380	-	
Reverse Transfer Capacitance	C _{rss}		-	325	-	
Switching Characteristics						
Total Gate Charge ⁴	Q _g	V _{GS} =4.5V, V _{DS} = 10V, I _D = 3A	-	38	-	nC
Total Gate Charge ⁴	Q _g	V _{GS} =3.9V, V _{DS} = 10V, I _D = 3A	-	33	-	
Gate-Source Charge ⁴	Q _{gs}		-	4.5	-	
Gate-Drain Charge ⁴	Q _{gd}		-	12	-	
Turn-on Delay Time ⁴	t _{d(on)}	V _{GS} =4.5V, V _{DD} = 16V, R _G = 6Ω, I _D = 3A	-	22	-	nS
Rise Time ⁴	t _r		-	41	-	
Turn-off Delay Time ⁴	t _{d(off)}		-	77	-	
Fall Time ⁴	t _f		-	21	-	
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface mounted on FR4 board using 1 square inch pad size, 1oz single-side copper.
3. Pulse Test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Guaranteed by design, not subject to product
5. The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=36A$.

Typical Characteristics

Figure 1. Output Characteristics

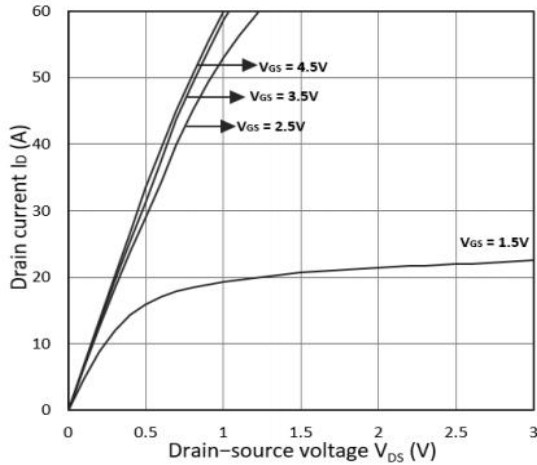


Figure 2. Transfer Characteristics

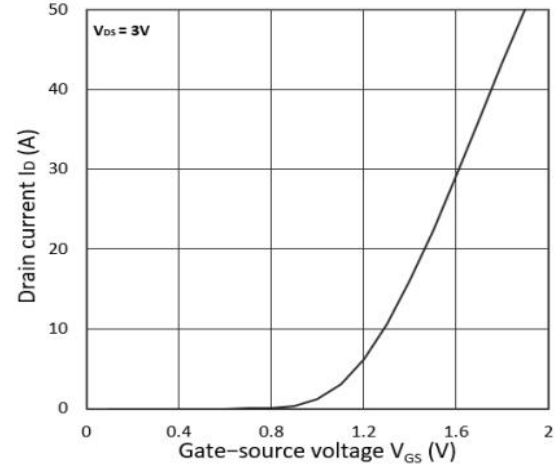


Figure 3. $R_{DS(ON)}$ vs. I_D

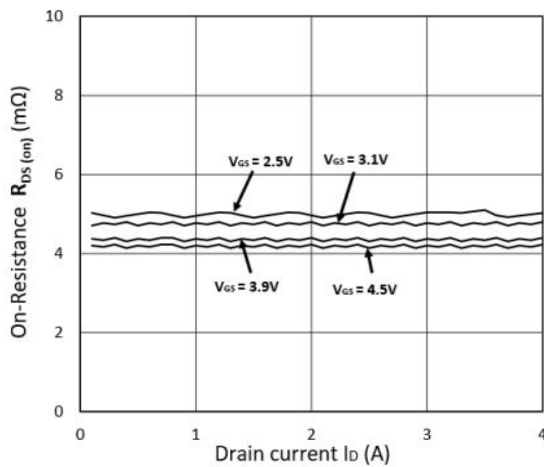


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

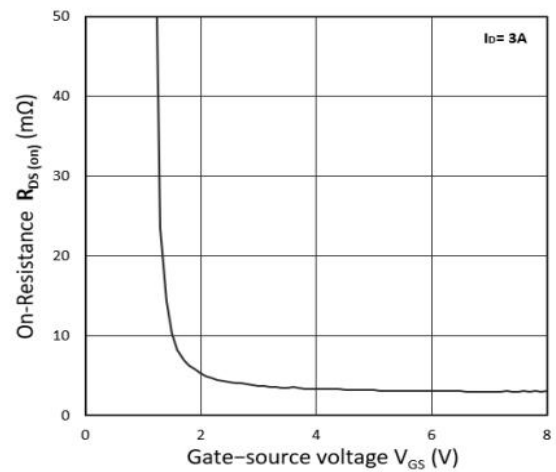


Figure 5. I_S vs. V_{SD}

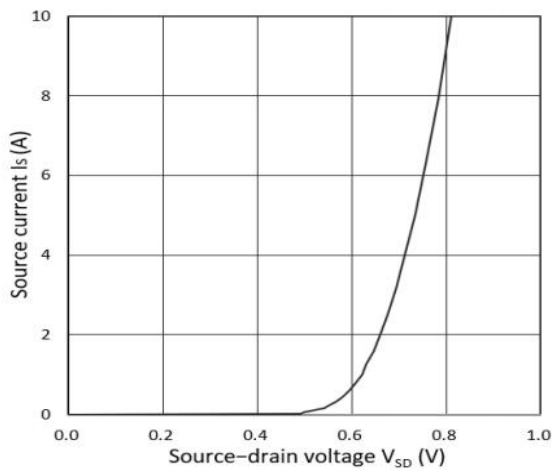
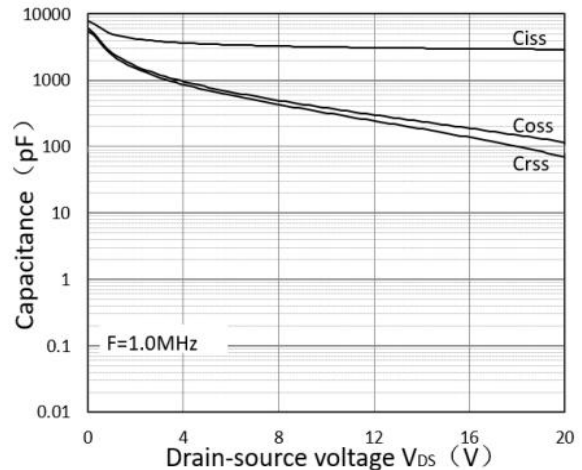


Figure 6. Capacitance Characteristics



Marking Codes

Part Number	CT56N02ZT	
Marking Code		Q56N02 = Device code XXXX XXX= Date code

Package Information

Qty: 3k/Reel

Mechanical Dimensions for PDFN3030-8L

